

<b>Notice of Allowability</b>	Application No.	Applicant(s)
	10/078,317	LIU ET AL.
	Examiner	Art Unit
	Alonzo Chambliss	2827

**-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address--**

All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTO-85) or other appropriate communication will be mailed in due course. **THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS.** This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.

- This communication is responsive to amendment A filed on 4/24/03.
- The allowed claim(s) is/are 1-15.
- The drawings filed on 15 February 2002 are accepted by the Examiner.
- Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
  - All
  - Some\*
  - None
 of the:
  - Certified copies of the priority documents have been received.
  - Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - Copies of the certified copies of the priority documents have been received in this national stage application from the International Bureau (PCT Rule 17.2(a)).
- \* Certified copies not received: \_\_\_\_\_.
- Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).
  - The translation of the foreign language provisional application has been received.
- Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application. **THIS THREE-MONTH PERIOD IS NOT EXTENDABLE**

- A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.

- CORRECTED DRAWINGS must be submitted.
  - including changes required by the Notice of Draftsperson's Patent Drawing Review (PTO-948) attached
    - hereto or 2)  to Paper No. \_\_\_\_\_.
  - including changes required by the proposed drawing correction filed \_\_\_\_\_, which has been approved by the Examiner.
  - including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No. \_\_\_\_\_.

Identifying Indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet.

- DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL.

**Attachment(s)**

<input type="checkbox"/> Notice of References Cited (PTO-892)	<input type="checkbox"/> Notice of Informal Patent Application (PTO-152)
<input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)	<input type="checkbox"/> Interview Summary (PTO-413), Paper No. _____.
<input type="checkbox"/> Information Disclosure Statements (PTO-1449), Paper No. _____.	<input type="checkbox"/> Examiner's Amendment/Comment
<input type="checkbox"/> Examiner's Comment Regarding Requirement for Deposit of Biological Material	<input checked="" type="checkbox"/> Examiner's Statement of Reasons for Allowance
	<input type="checkbox"/> Other

**DETAILED ACTION**

**Allowable Subject Matter**

1. The following is a statement of reasons for the indication of allowance subject matter: the prior art of record does not teach or suggest the combination of a lead frame with a plurality of first and second leads defining a chip bonding region, wherein the second leads extend and terminate in a plurality of contact pads within the chip bonding region. A die pad located at a sideways biased position in the chip-bonding region with a chip bonded thereon. A passive device is mounted between and connected to the contact pads with a plurality of bonding wires electrically connecting the chip, the passive device, and the first and second leads to one another in claims 1, 8, and 10.

A lead frame with a plurality of first and second leads defining a chip-bonding region, wherein the second leads extend and terminate in a plurality of contact pads within the chip-bonding region. A die pad located at a sideways biased position in the chip-bonding region with a chip bonded thereon in claim 15.

Any inquiry concerning the communication or earlier communications from the examiner should be directed to Alonso Chambliss whose telephone number is (703) 306-9143. The fax phone number for the Group is (703) 308-772 or 7724.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the group receptionist whose telephone number is (703) 308-7956.

**AC**/June 29, 2003



Alonzo Chambliss  
Patent Examiner  
Art Unit 2827